ABSTRACT

The present invention is intended to solve the problem of a conventional thermosetting conductive paste with respect to bonding-property between an internal electrode(s) and an external electrode(s) so as to provide a multilayer ceramic electronic part suitable for its mounting on a substrate and for its plating-treatment. The present invention relates to a multilayer ceramic electronic part, characterized in that it has an external electrode(s) formed from a thermosetting conductive paste comprising conductive particles having a high melting point, metal powder having a melting point of 300 °C or less and a resin(s).